BFR92A NPN 5 GHz wideband transistor Rev. 04 – 2 March 2009

**Product data sheet** 

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NXP Semiconductors



#### FEATURES

- High power gain
- Low noise figure
- Low intermodulation distortion.

#### APPLICATIONS

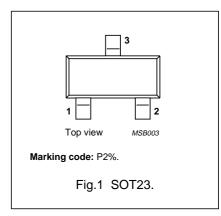
• RF wideband amplifiers and oscillators.

#### DESCRIPTION

NPN wideband transistor in a plastic SOT23 package. PNP complement: BFT92.

#### PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



#### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage		-	20	V
V <sub>CEO</sub>	collector-emitter voltage		-	15	V
I <sub>C</sub>	collector current (DC)		-	25	mA
P <sub>tot</sub>	total power dissipation	$T_s \le 95 \ ^{\circ}C$	-	300	mW
C <sub>re</sub>	feedback capacitance	$I_{C} = i_{c} = 0; V_{CE} = 10 V; f = 1 MHz$	0.35	_	pF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 15 mA; V <sub>CE</sub> = 10 V; f = 500 MHz	5	_	GHz
G <sub>UM</sub>	maximum unilateral power gain	$I_{C}$ = 15 mA; $V_{CE}$ = 10 V; f = 1 GHz; $T_{amb}$ = 25 °C	14	-	dB
		$I_{C}$ = 15 mA; $V_{CE}$ = 10 V; f = 2 GHz; $T_{amb}$ = 25 °C	8	-	dB
F	noise figure	$I_C = 5 \text{ mA}; V_{CE} = 10 \text{ V}; \text{ f} = 1 \text{ GHz};$ $\Gamma_s = \Gamma_{opt}; T_{amb} = 25 \text{ °C}$	2.1	-	dB
Vo	output voltage		150	-	mV

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	20	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	15	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	2	V
I <sub>C</sub>	collector current (DC)		_	25	mA
P <sub>tot</sub>	total power dissipation	$T_s \le 95 \text{ °C}$ ; note 1; see Fig.3	-	300	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	175	°C

#### Note

1.  $T_s$  is the temperature at the soldering point of the collector pin.

## BFR92A

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	$T_s \le 95 \ ^{\circ}C$ ; note 1	260	K/W

#### Note

1. T<sub>s</sub> is the temperature at the soldering point of the collector pin.

#### **CHARACTERISTICS**

T<sub>i</sub> = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector leakage current	I <sub>E</sub> = 0; V <sub>CB</sub> = 10 V	_	_	50	nA
h <sub>FE</sub>	DC current gain	$I_{C} = 15 \text{ mA}; V_{CE} = 10 \text{ V}; \text{ see Fig.4}$	65	90	135	
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0$ ; $V_{CB} = 10$ V; f = 1 MHz; see Fig.5	-	0.6	_	pF
C <sub>e</sub>	emitter capacitance	$I_{C} = i_{c} = 0; V_{EB} = 10 V; f = 1 MHz$	-	1.2	-	pF
C <sub>re</sub>	feedback capacitance	$I_{C} = i_{c} = 0; V_{CE} = 10 V; f = 1 MHz$	-	0.35	-	pF
f <sub>T</sub>	transition frequency	$I_C = 15 \text{ mA}; V_{CE} = 10 \text{ V}; f = 500 \text{ MHz};$ see Fig.6	-	5	-	GHz
G <sub>UM</sub>	maximum unilateral power gain (note 1)	$I_{C}$ = 15 mA; V <sub>CE</sub> = 10 V; f = 1 GHz; T <sub>amb</sub> = 25 °C	-	14	-	dB
		$I_{C}$ = 15 mA; V <sub>CE</sub> = 10 V; f = 2 GHz; T <sub>amb</sub> = 25 °C	-	8	-	dB
F	noise figure	$\label{eq:lc} \begin{array}{l} I_C = 5 \text{ mA; } V_{CE} = 10 \text{ V; } f = 1 \text{ GHz;} \\ \Gamma_s = \Gamma_{opt}; \ensuremath{T_{amb}} = 25 \ensuremath{^\circ C}; \\ \text{see Figs 13 and 14} \end{array}$	-	2.1	-	dB
		$\label{eq:lc} \begin{array}{l} I_C = 5 \text{ mA; } V_{CE} = 10 \text{ V; } f = 2 \text{ GHz;} \\ \Gamma_s = \Gamma_{opt}; \ T_{amb} = 25 \ ^\circ\text{C}; \\ \text{see Figs 13 and 14} \end{array}$	-	3	-	dB
Vo	output voltage	notes 2 and 3	_	150	-	mV
d <sub>2</sub>	second order intermodulation distortion	notes 2 and 4; see Fig.16	-	-50	-	dB

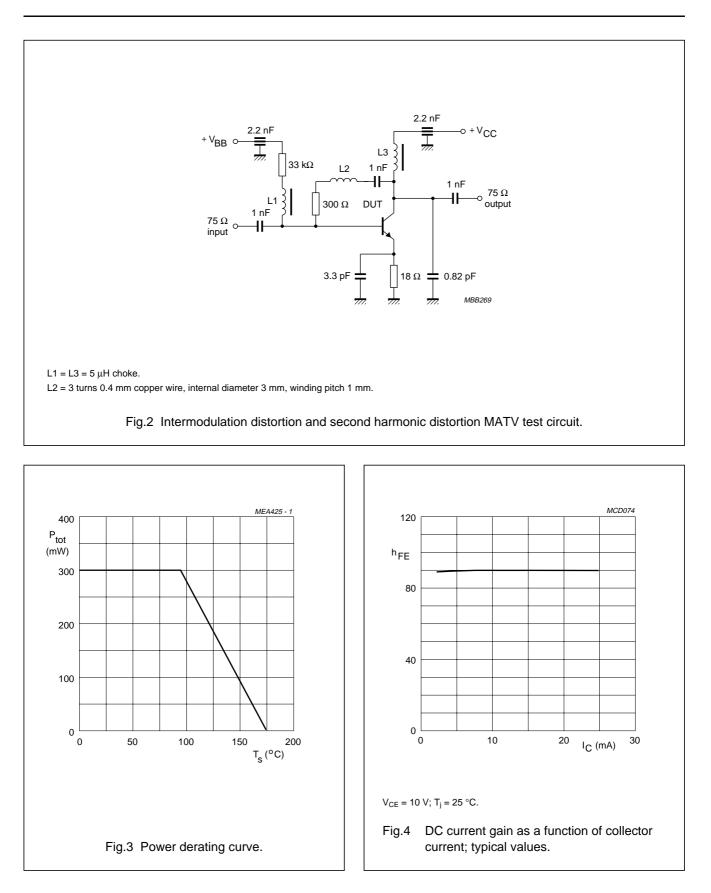
#### Notes

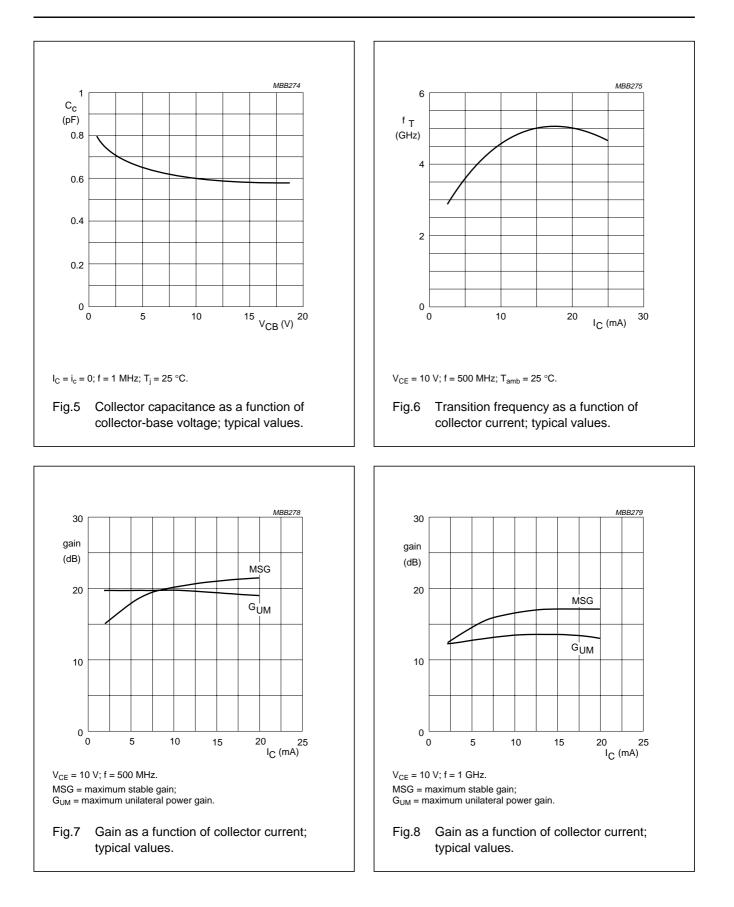
1.  $G_{UM}$  is the maximum unilateral power gain, assuming  $S_{12}$  is zero and  $G_{UM} = 10 \log \frac{|S_{21}|^2}{(1 - |S_{11}|^2)(1 - |S_{22}|^2)} d\dot{B}$ .

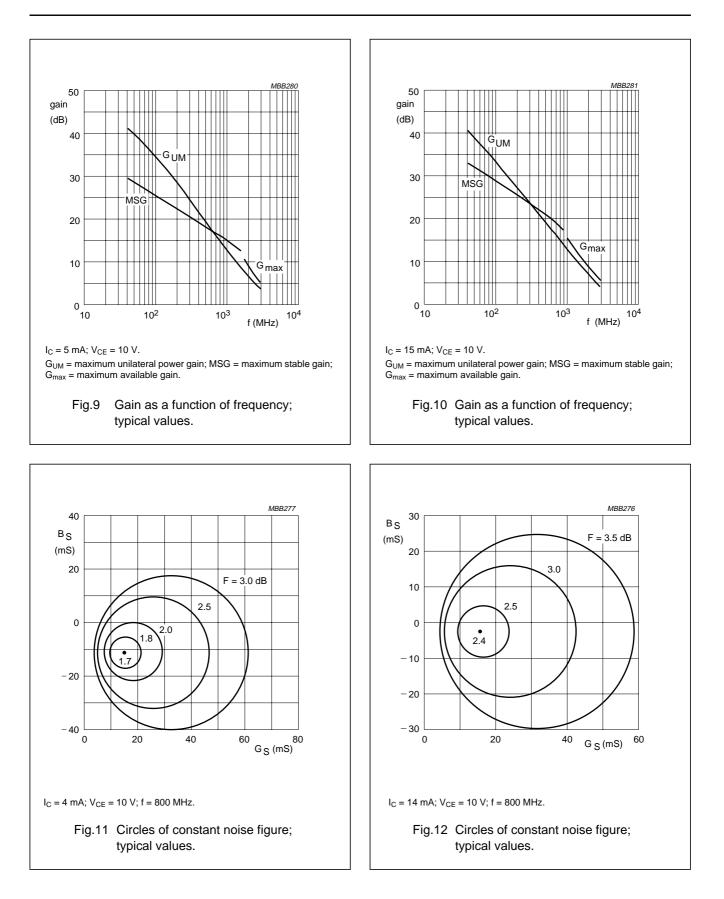
2. Measured on the same die in a SOT37 package (BFR90A).

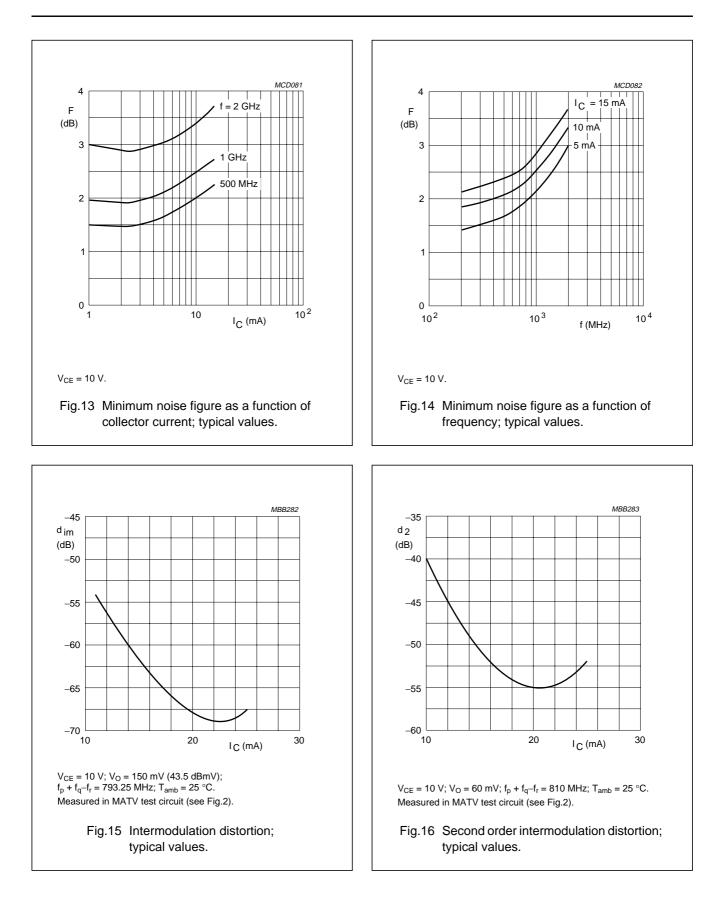
3.  $d_{im} = -60 \text{ dB}$  (DIN 45004B);  $I_C = 14 \text{ mA}$ ;  $V_{CE} = 10 \text{ V}$ ;  $R_L = 75 \Omega$ ; VSWR < 2;  $T_{amb} = 25 \text{ °C}$  $V_p = V_O \text{ at } d_{im} = -60 \text{ dB}; f_p = 795.25 \text{ MHz};$  $V_q = V_O - 6 \text{ dB}; f_q = 803.25 \text{ MHz};$  $V_r = V_O - 6 \text{ dB}; f_r = 805.25 \text{ MHz};$ measured at  $f_p + f_q - f_r = 793.25$  MHz.

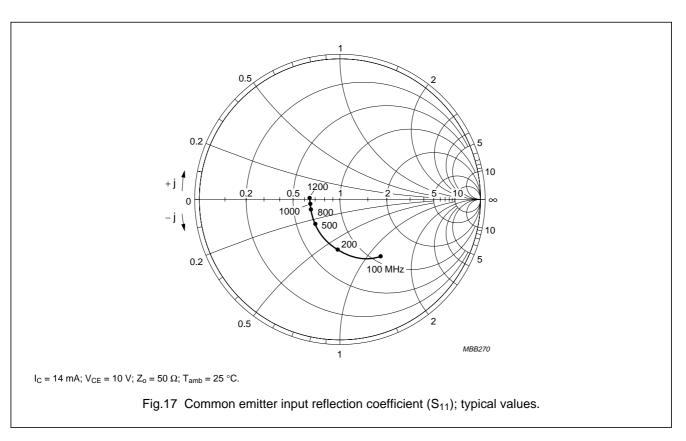
4.  $I_C = 14 \text{ mA}; V_{CE} = 10 \text{ V}; R_L = 75 \Omega; \text{VSWR} < 2; T_{amb} = 25 \text{ °C}$  $V_p = 60 \text{ mV}$  at  $f_p = 250 \text{ MHz}$ ;  $V_q = 60 \text{ mV}$  at  $f_q = 560 \text{ MHz}$ ; measured at  $f_p + f_q = 810$  MHz.

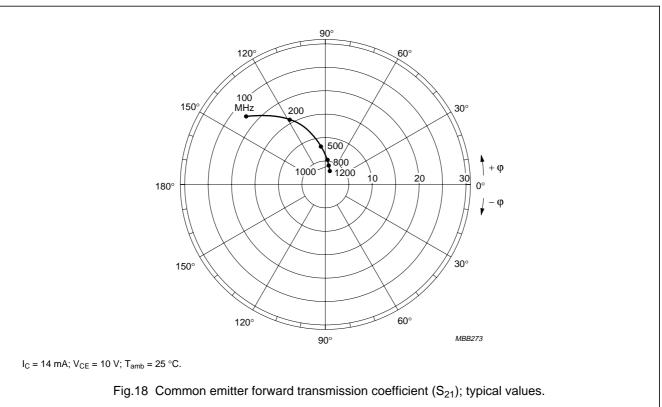


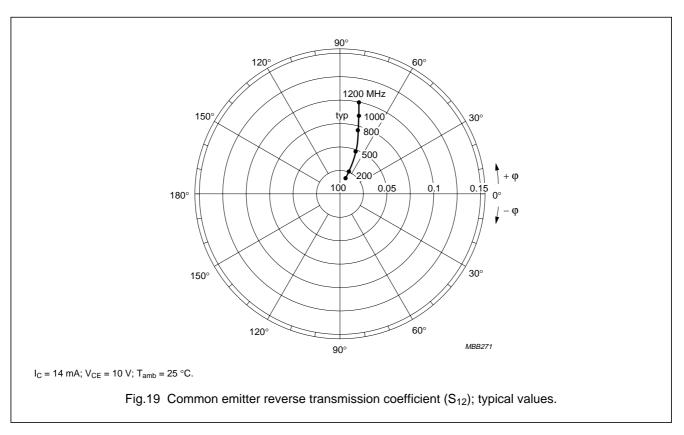


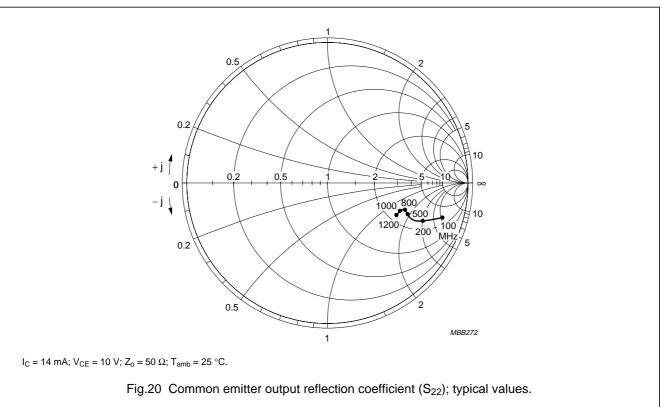










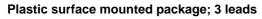


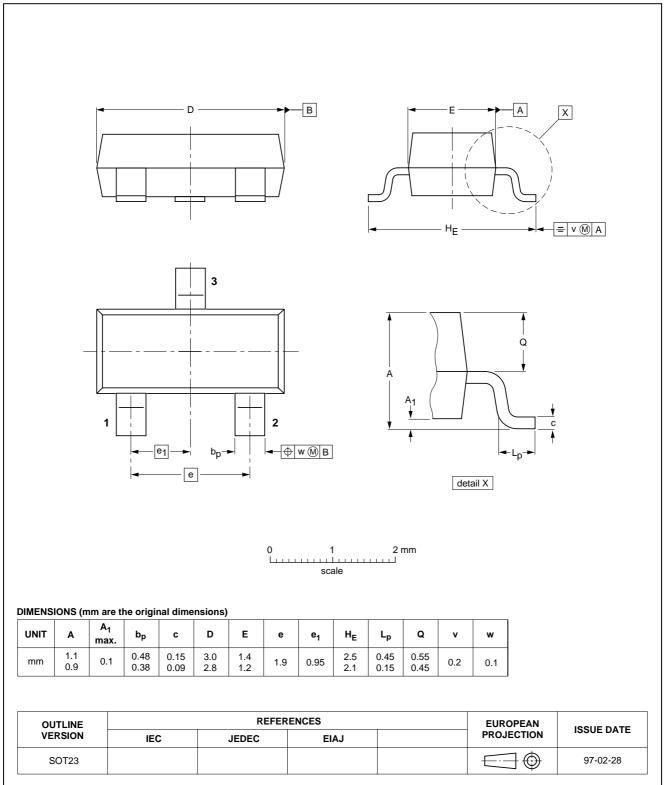
BFR92A

SOT23

# NPN 5 GHz wideband transistor

#### PACKAGE OUTLINE





## Legal information

## Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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# **Revision history**

Revision history				
Document ID	Release date	Data sheet status	Change notice	Supersedes
BFR92A_N_4	20090302	Product data sheet	-	BFR92A_N_3
Modifications:	<ul> <li>Fig.1 on pa</li> </ul>	ge 2; Figure note changed		
BFR92A_N_3	20080307	Product data sheet	-	BFR92A_2
BFR92A_2 (9397 750 02766)	19971029	Product specification	-	BFR92A_1
BFR92A_1	19950901	-	-	-

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